

NOTES:

1. ALL DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5-1982.

Δ DATUM PLANE [E-E] LOCATED AT MOLD PARTING LINE AND COINCIDENT WITH LEAD, WHERE LEAD EXITS PLASTIC BODY AT BOTTOM OF PARTING LINE.

Δ DATUMS [A-A] AND [D-D] TO BE DETERMINED AT CENTERLINE BETWEEN LEADS WHERE LEADS EXIT PLASTIC BODY AT DATUM PLANE [E-E].

Δ TO BE DETERMINED AT SEATING PLANE [C-C].

Δ DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION, ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1.

Δ DIMENSION D2 REPRESENTS THE TOTAL NUMBER OF TERMINALS.

Δ THESE DIMENSIONS TO BE DETERMINED AS DATUM PLANE [E-E].

Δ THE TOP OF PACKAGE IS SMALLER THAN THE BOTTOM OF PACKAGE BY 0.15 MILLIMETERS.

Δ DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08mm TOTAL IN EXCESS OF THE b DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED IN THE LOWER RADIUS OF THE FOOT.

10. CONTROLLING DIMENSION MILLIMETER.

11. DIMENSION D2 AND E2 REPRESENT THE SIZE OF THE EXPOSED PAD AND IS DEPENDENT ON THE BONDING DIAGRAM.

Δ DIMENSION D2 AND E2 REPRESENT THE SIZE OF THE EXPOSED PAD AND IS DEPENDENT ON THE BONDING DIAGRAM.

12. THIS OUTLINE CONFORMS TO JEDEC PUBLICATION 95 REGISTRATION MS-026, VARIATIONS ACB, ACC, ACD & ACE.

Δ A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT OF THE PACKAGE BODY.

15. EXPOSED PAD SHALL BE COPLANAR WITH BOTTOM OF PACKAGE WITHIN 0.05.

Δ CORNER CHAMFER OF EXPOSED DIE PAD SHALL BE WITHIN 10 μm.

JEDEC VARIATION ALL DIMENSIONS IN MILLIMETERS									
			ACB						
			MIN.	NOM.	MAX.				
A	0.05	0.05	0.05	1.20	0.15			13	
A4	0.95		1.00		1.05				
B			12.00 BSC.					4	
D			10.00 BSC.					7.8	
E			10.00 BSC.					4	
L	0.45		0.60		0.75			7.8	
N			44						
			0.80 BSC.						
b	0.30		0.37		0.45			9	
b1	0.30		0.35		0.40				
CCC					0.10				
DDD					0.20				

JEDEC VARIATION ALL DIMENSIONS IN MILLIMETERS									
MIN.			NOM.			MAX.			
ACC									
A	A1	L							
0.05	0.05	1.20				0.15			13
A4	0.95	1.00				1.05			
B		12.00 BSC.							4
D		10.00 BSC.							7.8
E		12.00 BSC.							4
L	0.45	0.60				0.75			7.8
N		52							
		0.65 BSC.							
b	0.22	0.32				0.38			9
b1	0.22	0.30				0.33			
CCC						0.10			
DDD						0.13			

JEDEC VARIATION ALL DIMENSIONS IN MILLIMETERS									
			ACD			DIMENSIONS			
			MIN.	NOM.	MAX.				
A	A1	L	0.05	0.20	1.20				
A4			0.95	1.00	0.15	1.05		13	
B				12.00 BSC.				4	
D				10.00 BSC.				7.8	
E				12.00 BSC.				4	
L				10.00 BSC.				7.8	
N			0.45	0.60	0.75				
			64						
			0.50 BSC.						
b			0.17	0.22	0.27			9	
b1			0.17	0.20	0.23				
CCC					0.08				
DDD					0.08				

JEDEC VARIATION ALL DIMENSIONS IN MILLIMETERS									
			ACE			B		L	
			MIN.	NOM.	MAX.				
A	0.05	0.05	0.05	1.20	0.15			13	
A4	0.95		1.00		1.05				
B		12.00 SSC						4	
D		10.00 SSC						7.8	
E		10.00 SSC						4	
L	0.45	0.60			0.75			7.8	
N		80							
		0.40 SSC							
b	0.13	0.18	0.23					9	
b1	0.13	0.16	0.19						
CCC			0.08						
DDD			0.07						

AMKOR/ANAM CONFIDENTIAL

Amkor Technology, Inc.
Chandler, Arizona, USA
Amkor Semiconductor, Inc.
Amkor Technology Philippines, Inc.
Manila, Philippines



PACKAGE OUTLINE: TOPF, 10X10 mm BODY,
1.00/0.10 mm FOR PL, 1.00 mm THICK,
(OPTIONAL: 4PAD)

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DO NOT SCALE DRAWING

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